

Troubleshooting Tips: Guidelines for Returns

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Return guidelines overview

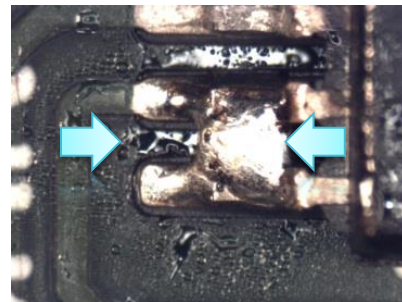
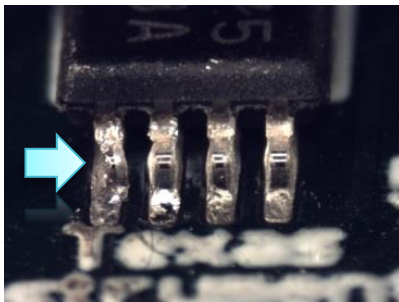
Five key steps for returns

- Carefully de-solder the TI product from the Printed Circuit Board (PCB)
- Verify and confirm issue on suspect TI product
- Return TI products in testable conditions
- Create your return request on ti.com
- Affix and return the TI product in proper container

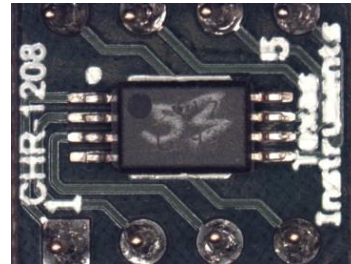
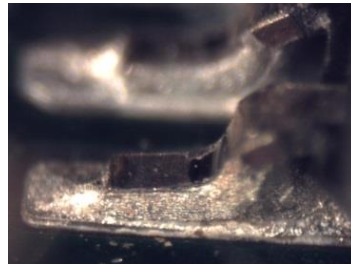
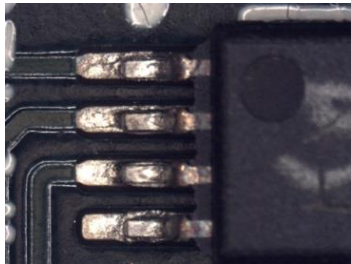
Verify and confirm issue on suspect TI product

- A thorough visual inspection should be performed prior starting the A-B-A swap
- A visual inspection improves the detection rate of hidden anomalies which may be overlooked, e.g.

- Bent leads/ lifted leads
- Solder bridges
- Flux contamination
- Damaged traces
- IC orientation



- Key inspection areas are
 - Leads/ footprints
 - Surrounding circuitry
 - Connected traces



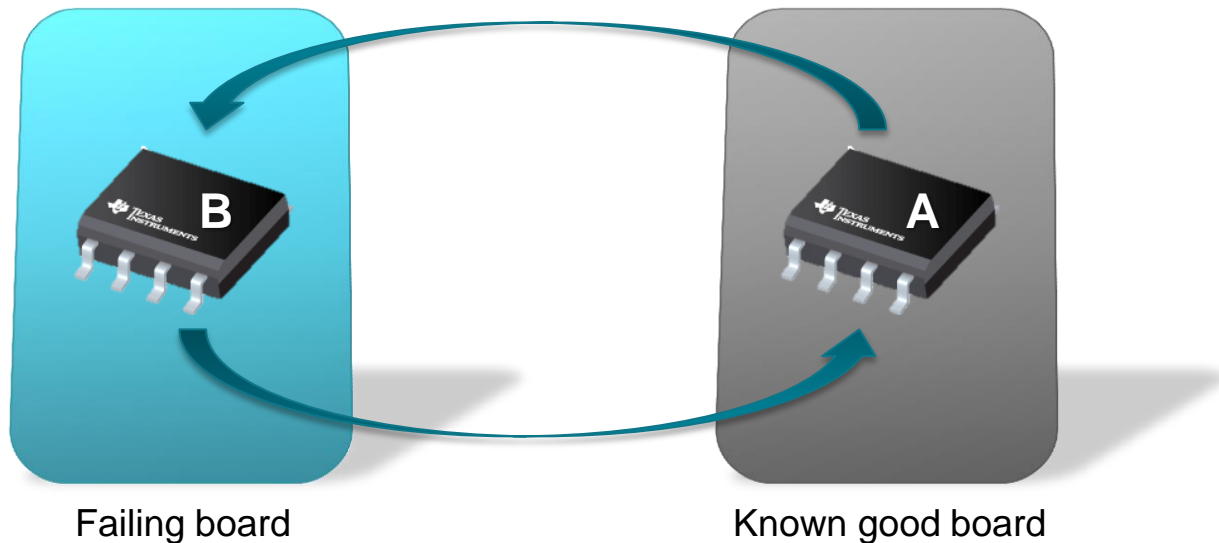
Verify and confirm issue on suspect TI product

Key benefits of the A-B-A swap

- Applies to troubleshooting both complex and simplistic electronic applications
- Detects assembly anomalies as e.g. solder bridges, excess soldered flux, cold solder joints and bent leads.
- Confirms that the TI product causes the issue on the application

Verify and confirm issue on suspect TI product

- 1) Remove the suspect TI product (A) and a known good TI product (B) from their boards.
- 2) Replace the suspect TI product (A) with a known good TI product (B).
- 3) Mount the suspect TI product (A) to a known good board.



More information on ti.com

TI Quality, Reliability & Packaging

- TI's quality and reliability processes
ti.com/quality
- Customer product returns
ti.com/returns
- Troubleshooting tips
 - Portal for Customer Product Returns
 - ESD Handling Guidelinesti.com/troubleshooting
- SMT & packaging application notes
ti.com/support-packaging/packaging-resources/SMT-and-application-notes.html

Application

- E2E support forum
ti.com/e2e
- TI Precision Labs
ti.com/PrecisionLabs